



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TECHNOLOGY CENTER 2800

Applicants: Richard R. Hall *et al.*

Examiner: Dinh, Tuan T.

Serial No.: 09/884,778

Art Unit: 2827

Filed: 06/19/2001

Dkt. No.: END920000187US1

For: **METHOD AND APPARATUS TO  
ESTABLISH CIRCUIT LAYERS INTERCONNECTIONS**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

This paper is being filed in response to the Final Office Action mailed November 7, 2002.

Applicant respectfully requests that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

Amendment

Please amend the above-referenced patent application as follows:

03/12/2003 JMC/MILLA 00000005 090457 09884778

01 FC:1201 In The Specification:

02 FC:1202 168.00 CH

36.00 CH  
Please delete the abstract and insert the following:

--An interconnect formed between layers of a circuit board, wherein a conductive element is embedded in an opening within a laminate of the circuit board, and wherein the conductive element forms at least one contact pad extending beyond a surface of the laminate.--

In The Claims

Claims 21-24 and 27-37 are pending in the application and are rejected.

Serial No. 09/884,778